

TMH, Inc.
Q3 FY2026 (Fiscal Year Ending November 2026)
Supplementary Materials for Consolidated Financial Results

Note : This document has been translated from the Japanese original for reference purposes only.
In the event of any discrepancy between this translated document and the Japanese original,
the original shall prevail.

TSE Growth Market / FSE Q-Board: 280A
October 15, 2026

To Our Shareholders



President & CEO
Taisuke Enami

The semiconductor market is growing remarkably, driven by technological innovations such as AI, quantum computing and IoT, and is gaining ever greater presence as a strategically important industry that shapes the competitiveness of every sector.

Against this backdrop, we believe that as semiconductor fabs worldwide keep operating and the installed base of semiconductor manufacturing equipment grows, the semiconductor manufacturing aftermarket in which we operate will continue to expand steadily.

We have supported the supply chains of semiconductor fabs through both engineering and digitalization (platforms), contributing to stable fab operations. We act with a **strong sense of mission to contribute to the revival of Japan's semiconductor industry and, by extension, Japanese manufacturing**. We will keep taking on challenges so that the semiconductor industry once again becomes a driving force that demonstrates Japan's industrial competitiveness to the world. We look forward to your continued expectations for our challenges and growth, and ask for your ongoing support.

AGENDA

- Part 1** **Q3 FY2026 Consolidated Results: Executive Summary**
- Part 2 Growth Strategy: Medium-Term Management Plan
- Part 3 Business Fundamentals
 - Business Overview / Market Environment /
Competitive Advantages
- Appendix

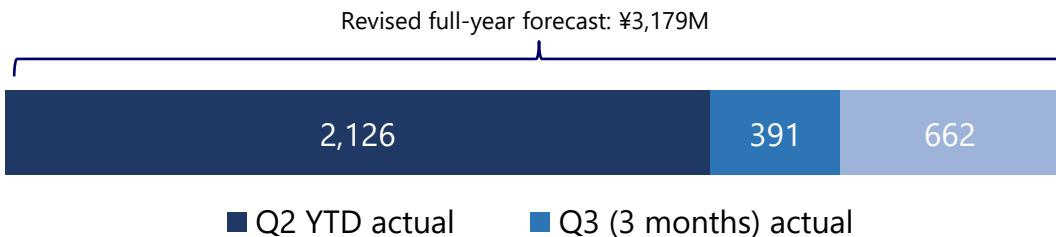
Q3 YTD consolidated results: net sales of ¥2.51bn and operating loss of ¥122M

■ Q3 YTD Consolidated Results

(Unit: ¥ million)

Item	Full-Year Consolidated Forecast (Revised July 15, 2026)	Q3 YTD Consolidated Results	Progress vs. Forecast (Difference)
Net sales	3,179	2,516 Prior-year Q3 YTD 6,929	79.2% (662)
Operating profit	*▲276	▲122.8 Prior-year Q3 YTD 209.1	Loss at 44.5% of FY forecast, within forecast range
Ordinary profit	▲285	▲129.0 Prior-year Q3 YTD 198.0	Loss at 45.2% of FY forecast, within forecast range

■ Progress of Net Sales vs. Full-Year Forecast



■ Key Points of Q3 YTD Results

Net sales | In line with revised forecast assumptions (backlog, sales plan)**Profit/loss** | Within plan, incl. upfront investment in distributor business**Outlook** | Assumptions unchanged; revised forecast maintained

*The full-year consolidated forecast reflects part of the valuation loss on used equipment inventory held

Advance-payment model underpins financial soundness; business foundation remains solid

Financial Base (as of end of Q3)

Cash and deposits **¥1,496M**

Secured M&A funds for future growth through the May 2026 equity financing

CCC (Cash Conversion Cycle) **34.1 days**

*CCC = Cash Conversion Cycle

*Inventory period + receivables period – payables period

Current ratio **440.3%**

*Current assets ÷ current liabilities

Adjusted equity ratio **54.1%**

*After deducting advances received (contract liabilities)

Business Base

400+ companies

Customers — direct trading accounts with nearly all semiconductor makers in Japan

200+ companies

Global supplier network — reduced dependence on specific suppliers

50%+

LAYLA-EC adoption rate among Japanese semiconductor fabs — established as procurement infrastructure

KPIs: Parts & repair above prior year; equipment sales diversifying procurement channels

Parts sales & repair services exceeded the prior year and remained solid as a stable revenue source
Equipment sales order backlog down 68% YoY. Diversifying procurement channels to build orders for next fiscal year

(Unit: ¥ million)

KPI		End of Q3 FY2025	End of Q3 FY2026	YoY change
Leading indicator (future performance)	Equipment sales order backlog	1,680	530	-68%
Lagging indicators (past performance trend, cumulative)	(Cross-border EC platform) Parts sales & repair net sales	768	778	+1%
	(Engineering) Equipment sales net sales	6,161	1,738	-72%
Productivity indicators (net sales & net income cumulative)	Net sales per employee	169	50	-70%
	Net income per employee	3.3	▲ 1.8	—

Order backlog refers to the total revenue expected in the future from order contracts. An increase in order backlog therefore indicates an expected contribution to future results

Business Topics: Strengthening Global Sales and Technical Capabilities

Established a subsidiary in China to further strengthen sales and growth

Overview

■ Subsidiary in Shanghai, China began operations in October 2026

- Several Chinese employees stationed locally

■ Purpose of establishment

① Deepen accounts

- Direct transactions with end users; building local networks and hotlines

Aiming to improve margins, strengthen competitiveness in the Chinese market and improve collections

② New businesses

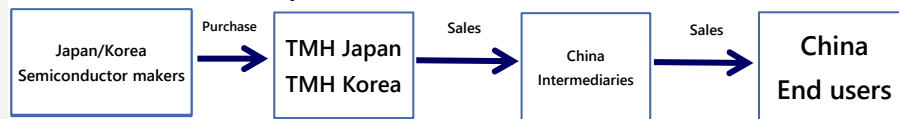
- Considering future local manufacturing, processing and sales of semiconductor materials/parts



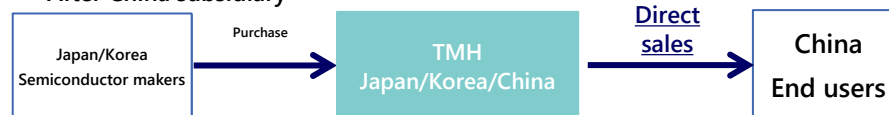
① Deepen accounts

Direct sales to end users without intermediaries

<Before China subsidiary>

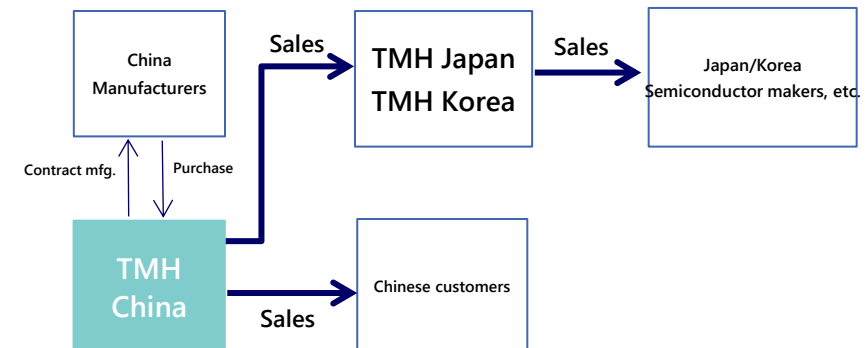


<After China subsidiary>



② New businesses

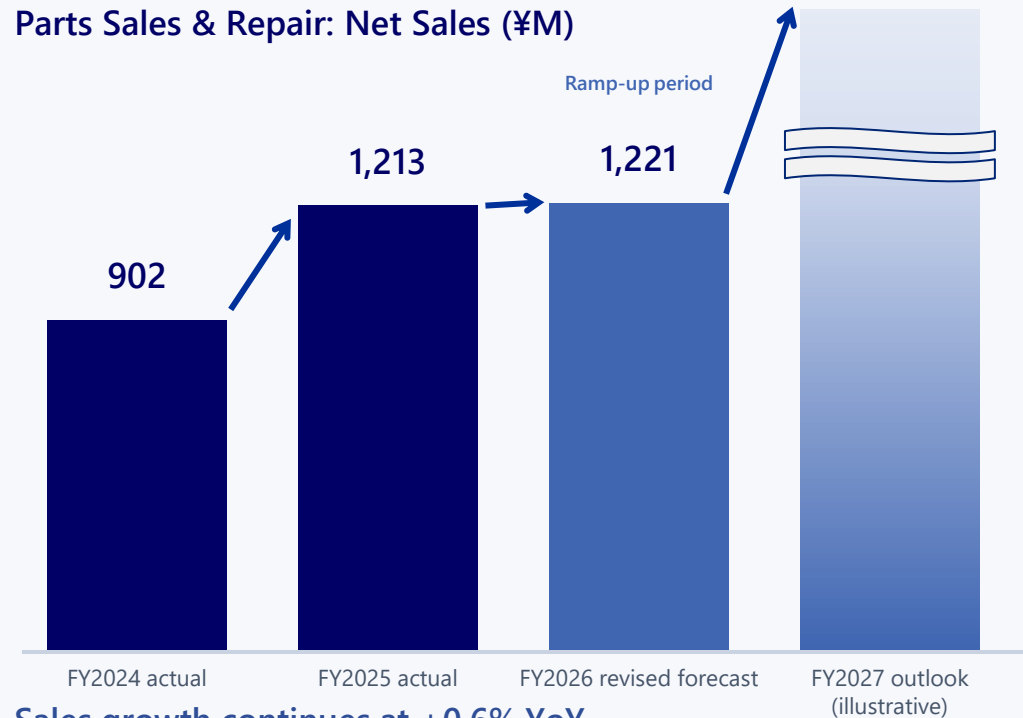
Leverage Chinese subsidies and production base to sell to Japan and others, strengthening the supply chain



Cross-border EC: Parts sales & repair services keep growing; re-acceleration in FY2027

Parts sales & repair services using cross-border EC plan to re-accelerate by strengthening the supplier base

Parts Sales & Repair: Net Sales (¥M)



Sales growth continues at +0.6% YoY

LAYLA-related sales up at a CAGR of +34.9% since FY2022

FY2027 Re-acceleration Driver: Stronger Supplier Base

- Signed a domestic distributor agreement with the Japanese subsidiary of Entegris, a leading U.S. semiconductor materials maker
- Materials/consumables are repeat purchases tied to chip output, directly growing recurring revenue

Partnering with a world-leading materials maker to expand procurement and product range and re-accelerate EC

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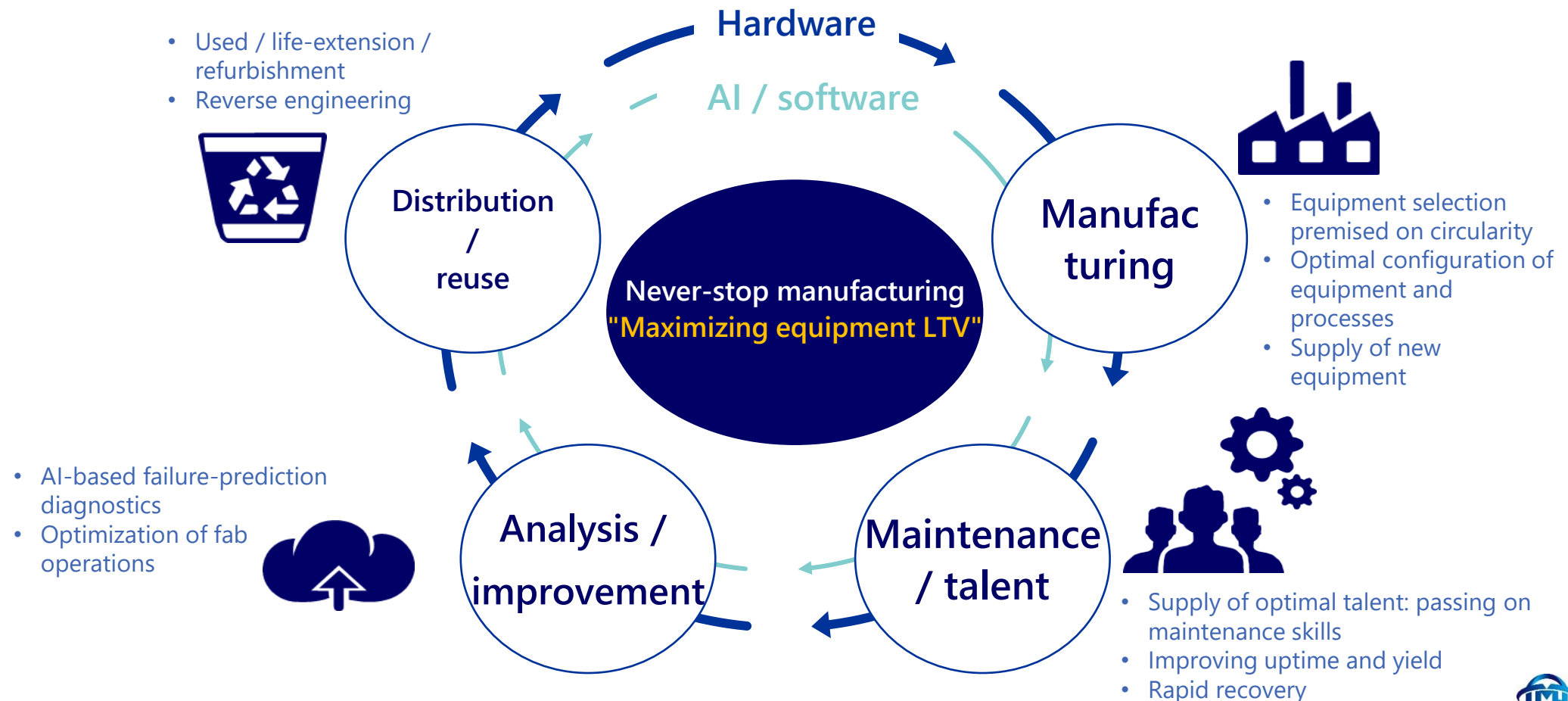
Appendix

The Future Semiconductor Manufacturing Supply Chain as We See It

Toward a model that prioritizes a highly efficient supply chain premised on a "circular" business

- In a society of rising uncertainty—resource depletion, conflict, and fragmentation—circular design to achieve "never-stop manufacturing" is gaining importance.
- From "keeping operations running via failure prediction" and "value that includes uptime, yield, and talent retention" to a shift

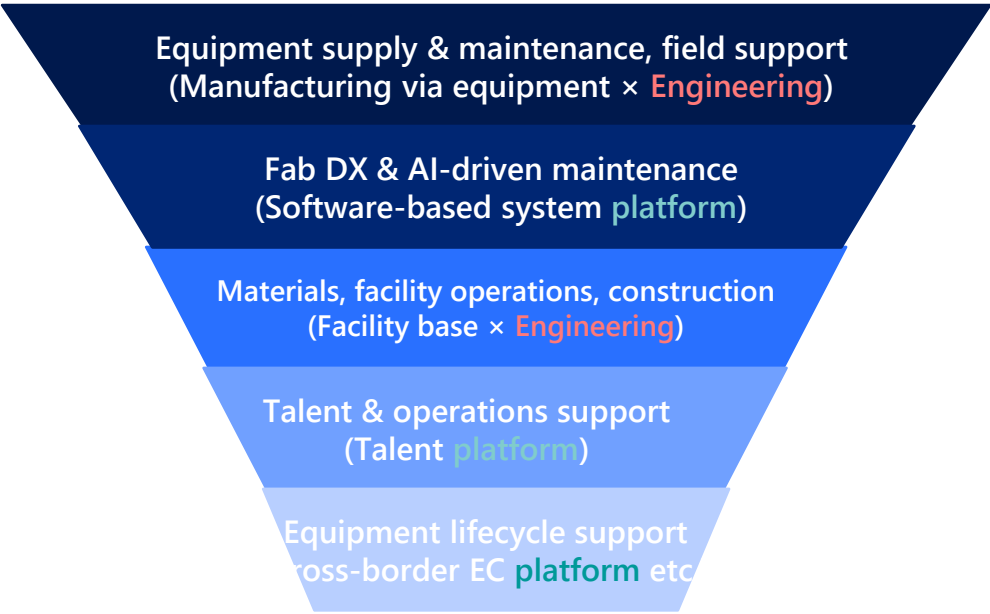
Circular design



Medium- to Long-Term Target: Vision1000
We aim to grow into a company with net sales of ¥100bn over the medium to long term

TMH will evolve from after-sales equipment lifecycle support into a “Semiconductor Manufacturing Integrator” that supports manufacturing end-to-end through platforms

Vision1000



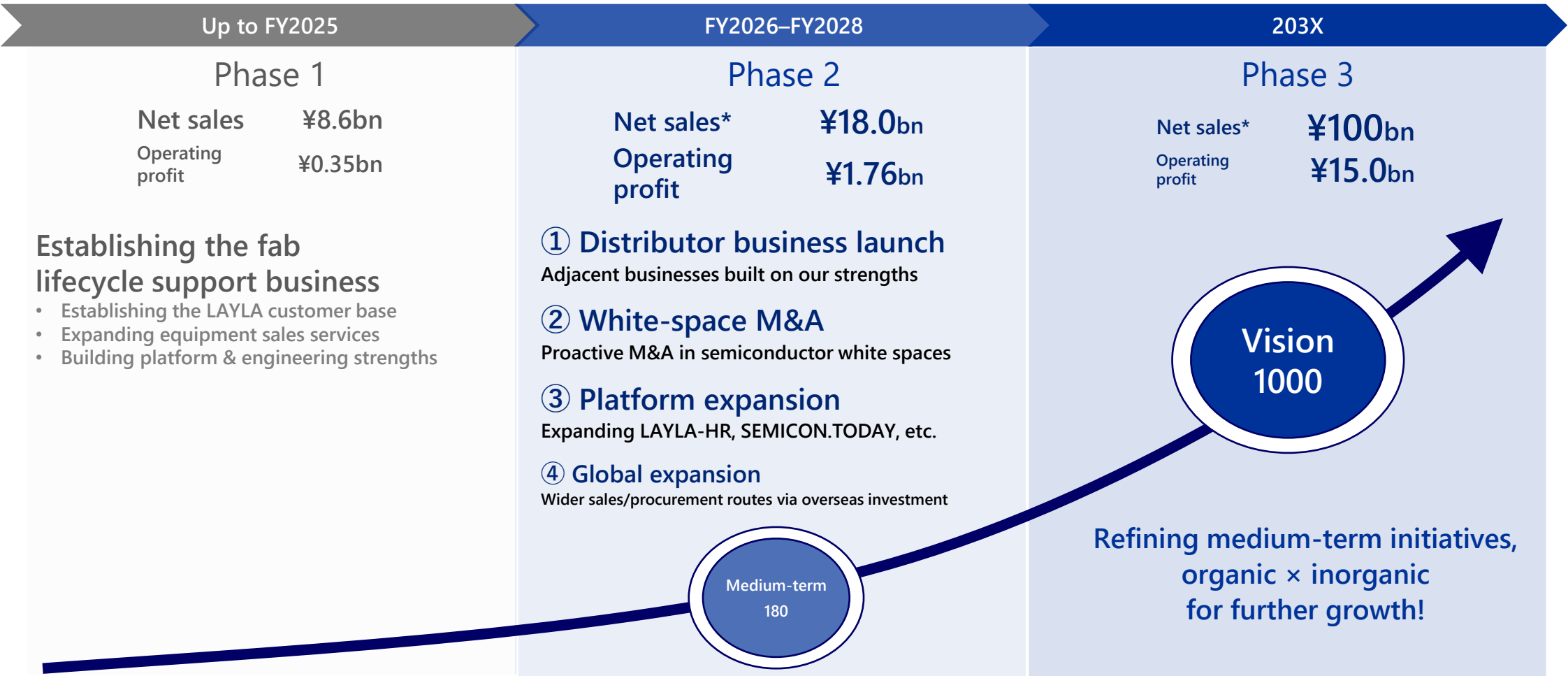
Toward a Semiconductor Manufacturing Integrator Solving diverse fab challenges through Engineering × Platforms	
Manufacturing	Services : Outsourced operation of entire fabs; contracts for productivity improvement and cost optimization Revenue model : Comprehensive contracts for overall fab operation; high value-added model
DX & AI predictive maintenance	Services : Improving/renewing legacy fab systems via DX and AI Revenue model : SaaS model; high profitability from software margins
Materials supply Facility mgmt. Construction	Services : Stable chemical/gas supply; fab infrastructure management (ultrapure water, HVAC, waste treatment); construction Revenue model : Recurring revenue + high margins
Talent & operations support	Services : Talent platform services; engineer education and training programs Revenue model : Continuing contracts (quasi-recurring)
Equipment lifecycle support	Services : Parts sales & repair via cross-border EC; equipment sales leveraging engineering capabilities; other related engineering services Revenue model : Includes one-off transactions; partly quasi-recurring

Filling the white spaces meets the requirements for keeping semiconductor fabs running
Toward "non-stop manufacturing"

Vision1000 Roadmap

From after-sales services to a “Semiconductor Manufacturing Integrator”: Roadmap to ¥100bn

Accelerating organic growth and pursuing inorganic growth to achieve Vision1000

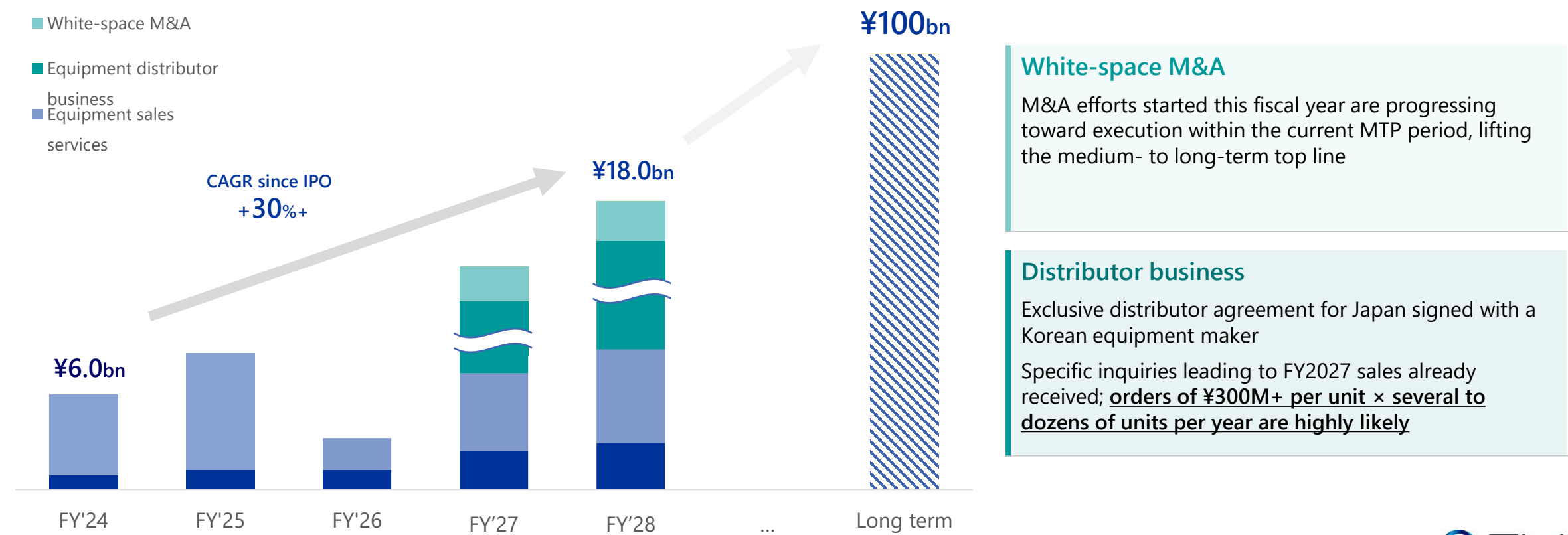


*Net sales are presented on a gross merchandise value (GMV) basis

Medium- to Long-Term Growth Image (Net Sales)
Broadening the portfolio through distribution and M&A, aiming for ¥100bn in net sales

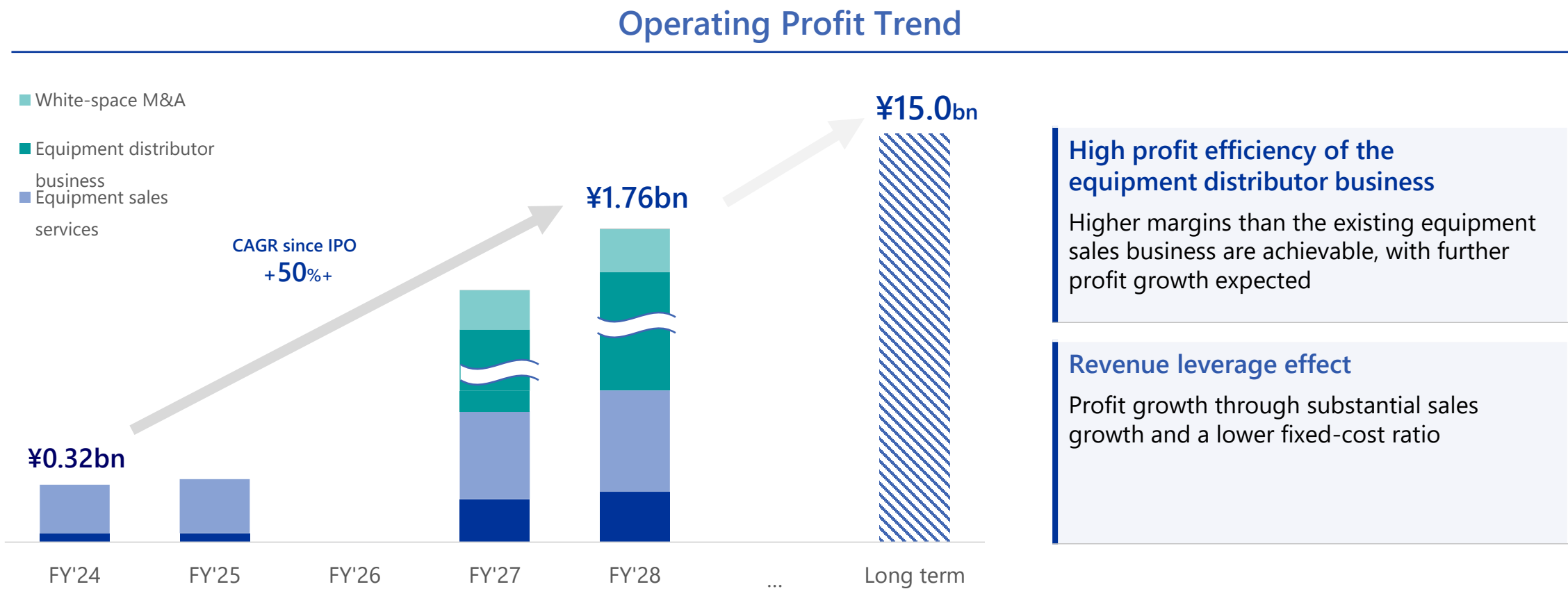
- Adding the **distributor business** and **white-space M&A** as medium- to long-term growth drivers
- A distributor is effectively each equipment maker's "face" in Japan, not a mere intermediary
Leveraging our platform and engineering strengths to create synergies with existing businesses

Net Sales (GMV) Trend



Medium- to Long-Term Growth Image (Operating Profit)
Targeting ¥15bn operating profit through high-margin growth and an evolving earnings structure

- Adding the equipment distributor business and white-space M&A as growth drivers
- With growth of the high-margin distributor business and a lower fixed-cost ratio,
operating profit CAGR since IPO to exceed +50%



Medium-Term Management Plan

Aiming for a dramatic increase in operating profit to ¥1.76bn in FY2028

- FY2026: lower sales and an operating loss expected, due to fewer equipment procurement opportunities and upfront hiring for the distributor business
- Medium term: expanding the new distributor business, white-space M&A and their synergies to deliver operating profit of ¥1.76bn

CAGR

(Unit: ¥ million)

	FY2025 actual	FY2026 Revised forecast	FY2027 Plan	FY2028 Plan	FY2028 vs. FY2025 (% change)
Net sales	8,628	3,179	10,336	12,805	+4,176 (+48.4%)
Net sales (GMV)*	8,628	3,179	14,153	18,291	+9,662 (+112.0%)
Gross profit	970	443	2,967	3,457	+2,486 (+256.3%)
(Gross margin)	11.2%	14.0%	28.7%	27.0%	+15.8pt
Operating profit	355	▲276	1,421	1,767	+1,411 (+396.9%)
(Operating margin)	4.1%	–%	13.8%	13.8%	+9.7pt

* For the equipment distributor business, figures assume transactions recorded on a net basis in the financial statements are recorded on a gross basis

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TMH, Inc.'s name is formed from the initials of
Technology Makes Happiness

MISSION

Technology Makes Happiness
Supporting the future of semiconductors and contributing to social progress through people and technology

VISION

A company where people grow, value is created, and global markets are built

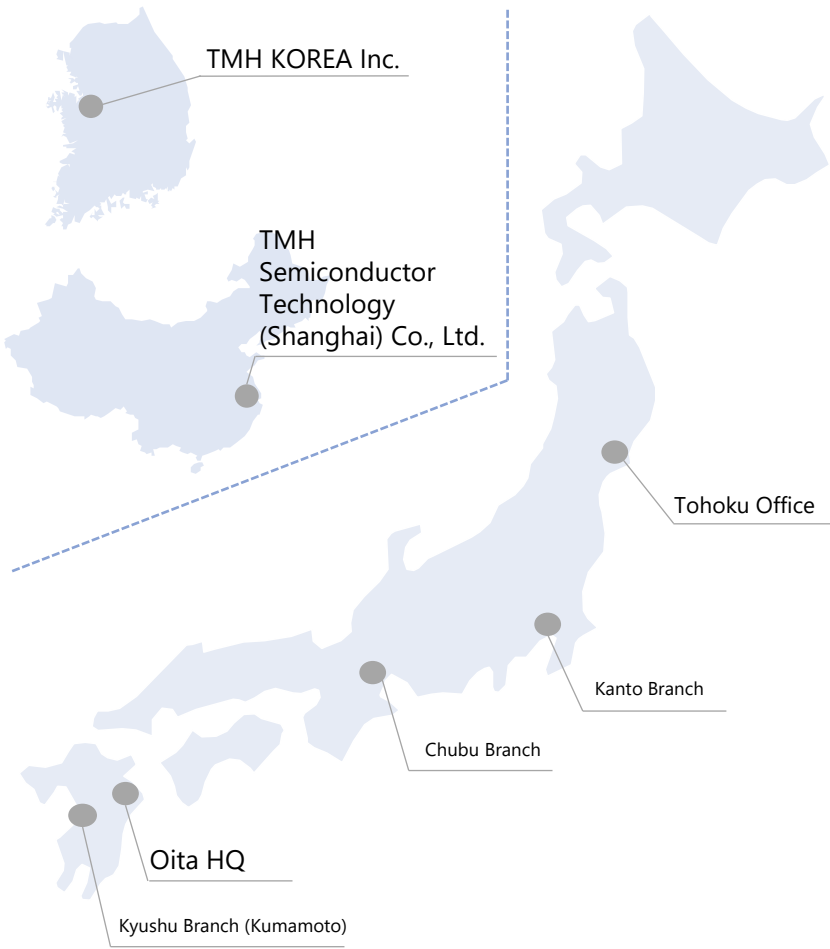
VALUE

I. Individual	V1	Take on challenges freely; see them through with responsibility	II. Customers	V3	For our customers, with every capability we have	III. Organization	V5	Go beyond boundaries; take on challenges as one
	V2	Turn untapped potential into results		V4	Only by exceeding expectations do we earn trust		V6	Unite individuality to pioneer the world

Company Overview

Company name	TMH, Inc.
President & CEO	Taisuke Enami
Head office	3-14-6 Shimogori-kita, Oita City, Oita Prefecture
Established	March 9, 2012
Employees	50 (as of end of August 2026, consolidated)
Capital	¥312.89M (as of end of August 2026)
Business	Semiconductor manufacturing field solutions business (Sales and repair of equipment and parts; operation of cross-border EC site LAYLA-EC)
Offices	Oita HQ, Chubu Branch, Kanto Branch, Tohoku Office, Kyushu Branch (Kumamoto)
Overseas subsidiaries	2 (Pyeongtaek, Korea; Shanghai, China)

5 sites in Japan + Korea & China



Management Team

Composed of semiconductor and supply chain experts amid a shortage of semiconductor equipment specialists



Taisuke Enami
Representative Director
CEO

After graduating from Waseda University, joined Toshiba Corporation. Became independent after recognizing issues in supplier management at Toshiba. In 2020, TMH was selected by Oita Prefecture as a regional leading company



Kenichi Katsuki
Director, CPO

After joining Toshiba Corporation, engaged in purchasing and procurement for over 20 years. In 2012, handled materials procurement for the semiconductor division at Toshiba HQ, achieving annual cost reductions and improvements of several billion yen. Joined TMH in 2016



Maki Seki
Director, CFO

Engaged in management reform at a major operating company and Deloitte Tohmatsu Consulting. Led many projects from a supply chain perspective, including visualization of global cost structures and M&A. Joined TMH in 2015

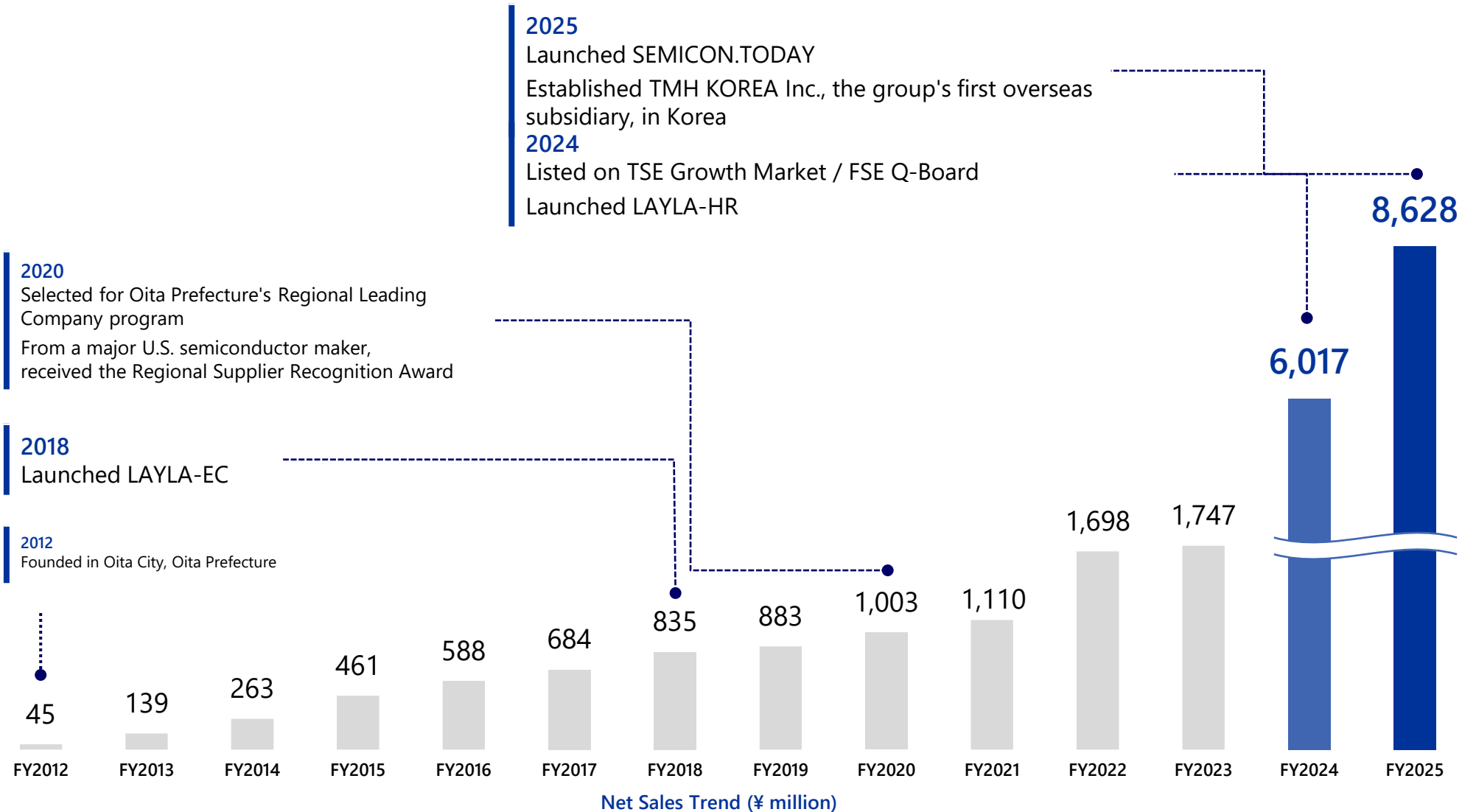


Osamu Nogimura
Outside Director

After graduating from Nagoya University, joined Hitachi, Ltd. Served as General Manager of Production at Renesas Technology, Executive Officer and General Manager of Production at Renesas Electronics, and President of Renesas Semiconductor Package & Test Solutions. Consistently engaged in semiconductor manufacturing

History

Continuous growth since founding, driven by the LAYLA platform and expansion of equipment sales





A leading company solving the many social challenges facing the semiconductor industry

Domain	Value Provided	Features
The vast semiconductor industry	Extending equipment life Reducing maintenance costs	Niche top and High growth

Why We Are Needed

Aging semiconductor fabs face a host of supply chain challenges

Procurement Challenges

- Many Japanese fabs are **obsolete and aging**, with many **legacy** semiconductor tools, making **parts procurement difficult**
- Procurement of legacy equipment parts relies mainly on individual know-how (**lagging digitalization**)

Manufacturing Challenges

- With demand rising rapidly due to IoT (Internet of Things), **demand for older equipment continues**
- With the prolonged slump of Japan's semiconductor market, **engineering talent has dried up**
- At legacy fabs, **dependence on individuals for equipment maintenance is the norm**, and equipment troubles escalate into quality issues and major delivery delays

Logistics Challenges

- **Routine storage of older equipment** bought for parts ends up **squeezing production space**

Our Vision for the Future

By solving the diverse challenges of semiconductor manufacturing,
we support the revival of Japanese manufacturing

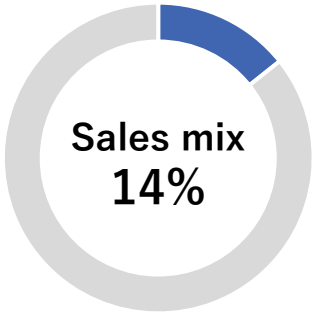
Business Description: Overview of the Semiconductor Manufacturing Field Solutions Business

Supporting fab operations by providing total solutions

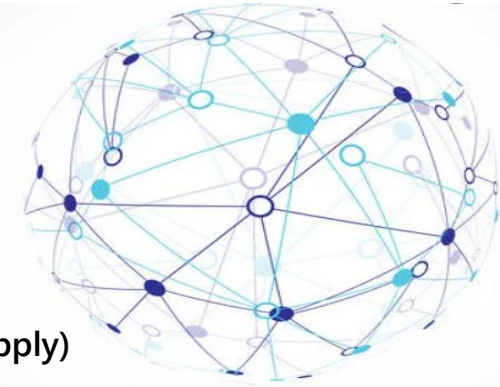
Total solution services for semiconductor fabs

Parts sales & repair services using cross-border EC platforms

Using platforms to trade semiconductor equipment and parts worldwide

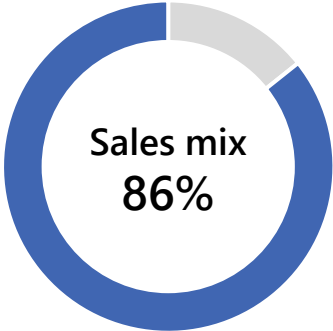


- [Services]
- ✓ Supply of rare parts
 - ✓ Broad range of repair services
- [Track record]
- ✓ 200+ high-quality global suppliers (diverse maintenance and parts supply)
 - ✓ 365,000+ items; adopted by 50%+ of Japanese semiconductor fabs



Equipment sales services leveraging engineering capabilities

Equipment dismantling, relocation, removal, process tuning and start-up services



- [Services]
- ✓ End-to-end service from dismantling specialized equipment to removal
 - ✓ Improving yield through process tuning of older equipment
- [Track record]
- ✓ Supplier award from a major U.S. semiconductor maker
 - ✓ Proven reliability (100+ units of semiconductor equipment traded)

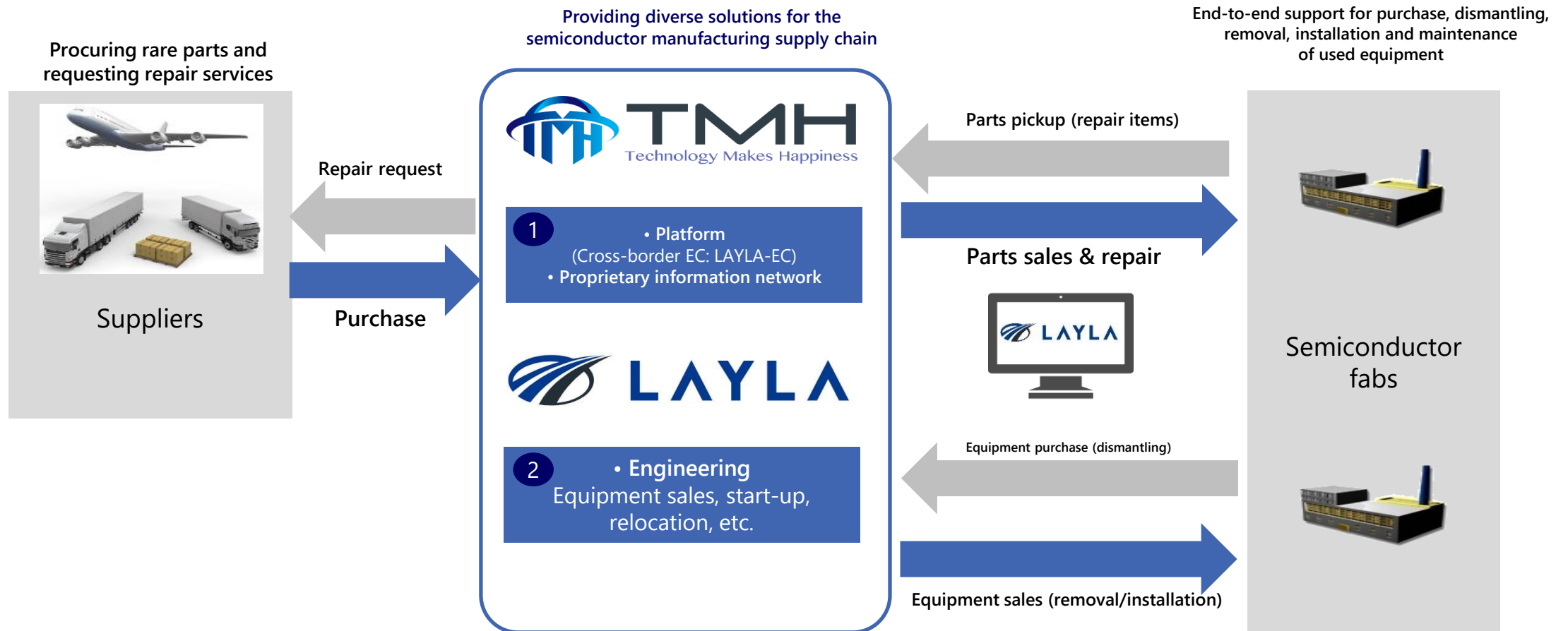


Sales composition based on FY2025 results

Business Flow

Combining an EC platform with engineering to support sustainable fab operations

- Collaborating with engineering firms and suppliers worldwide to offer broad solutions, from parts repair and sales to yield improvement and buyback of unused equipment and parts
- LAYLA aggregates worldwide equipment and parts data, streamlining equipment procurement
Contributing to efficient, sustainable equipment operation at fabs

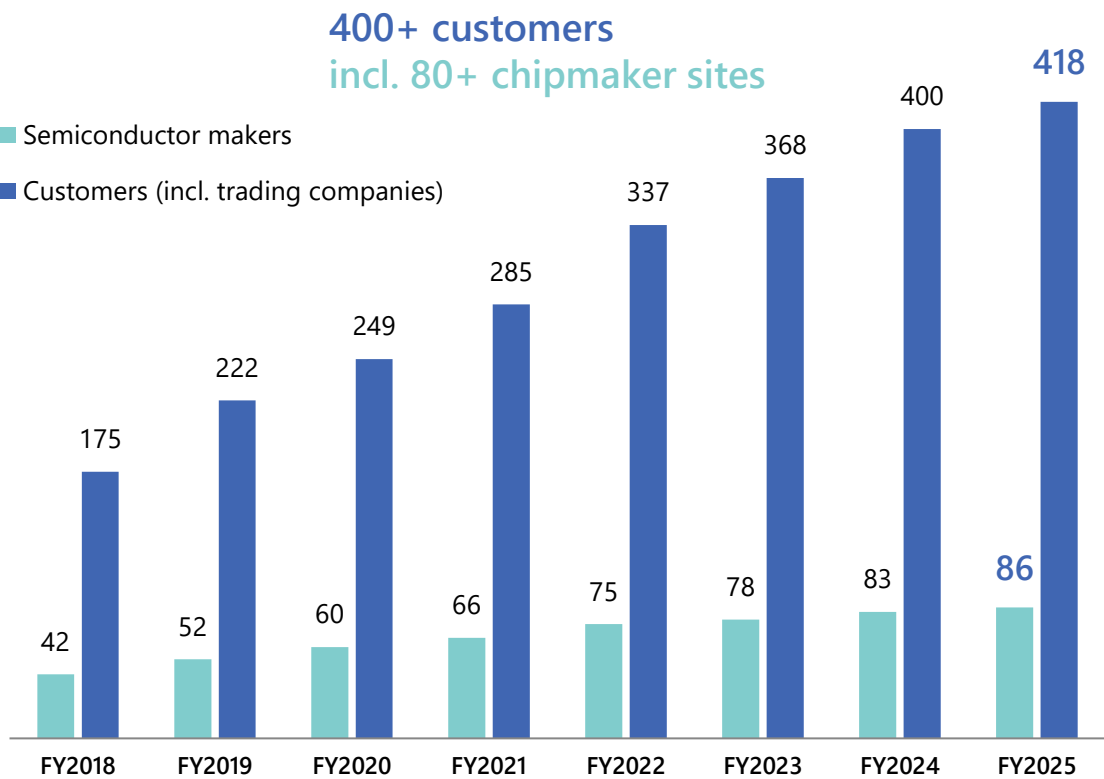


Customers

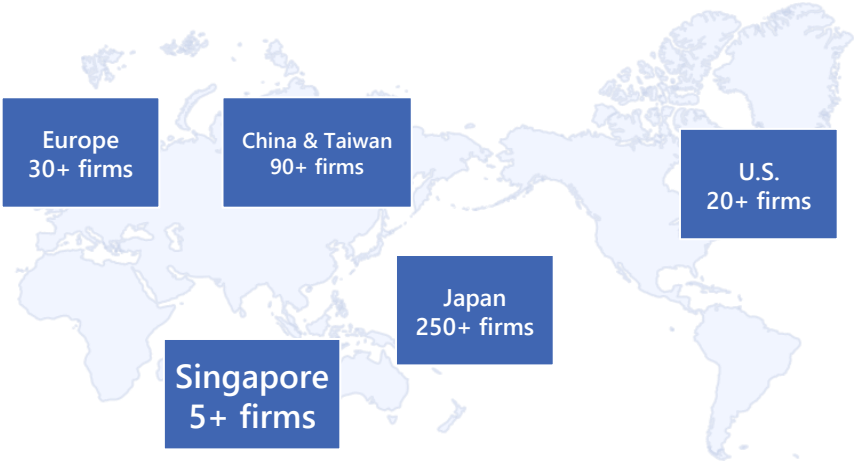
Expanding direct trading with Japanese chipmakers via the procurement power of our cross-border EC site

- [Nearly all semiconductor makers in Japan](#) have opened direct trading accounts with us
- [Semiconductor makers account for 80+ customer sites](#). Total customers, including others, exceed 400 companies
- Through LAYLA-EC, [transactions with overseas semiconductor makers are also expanding](#)

Number of Customers



Customer Map by Country



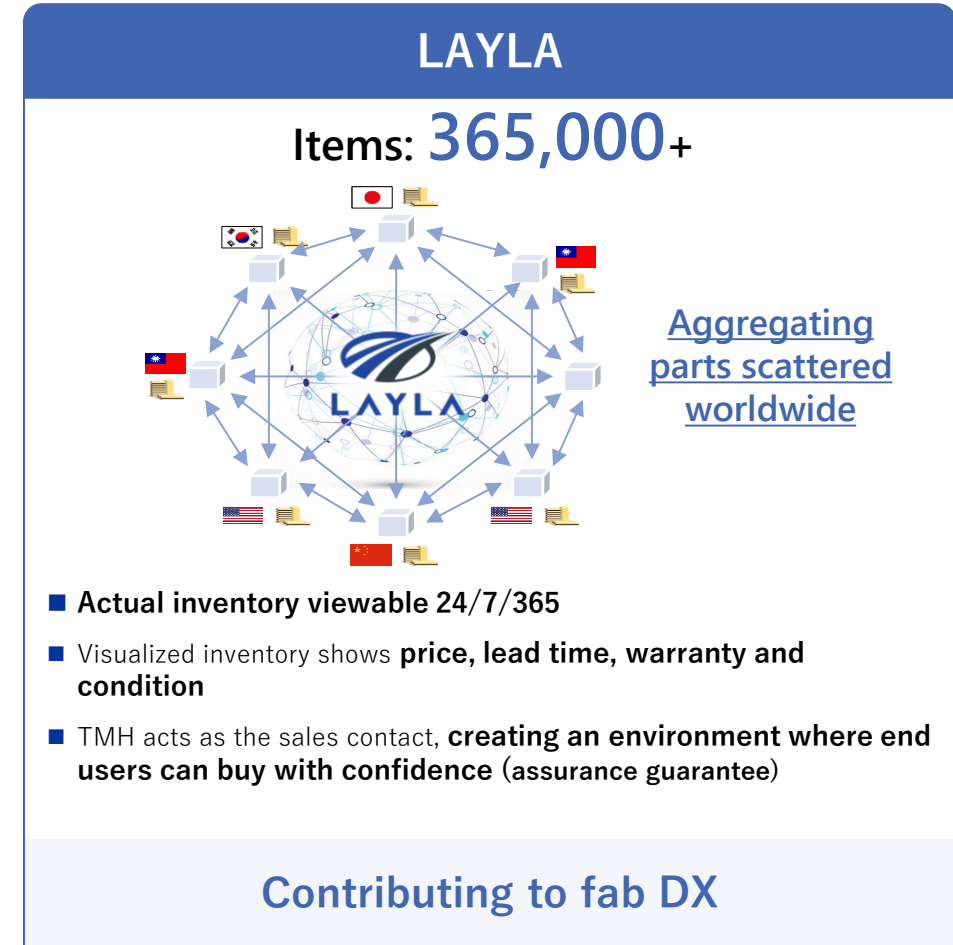
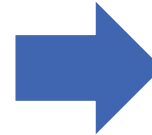
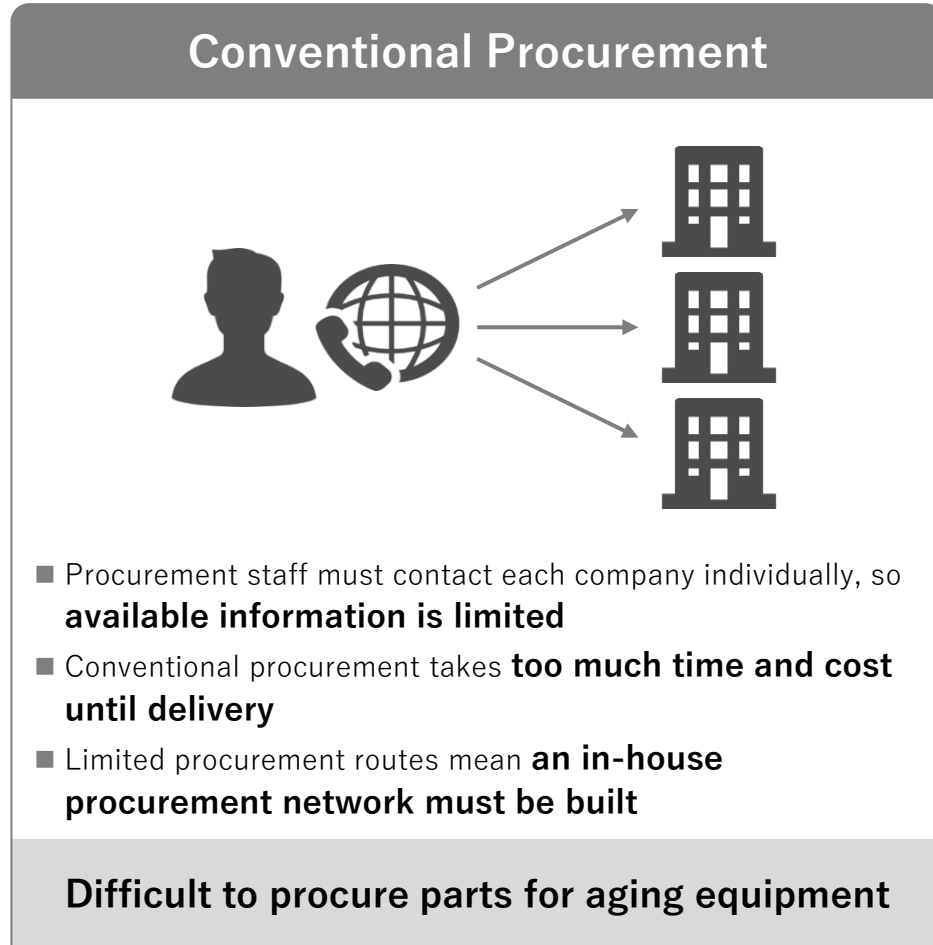
Major Customers

- Kioxia
- Texas Instruments
- Sony Semiconductor Manufacturing
- Renesas Electronics
- SUMCO Group
- Toshiba Group
- LAPIS, etc.

Value Provided by LAYLA

Established a platform that visualizes actual inventory worldwide

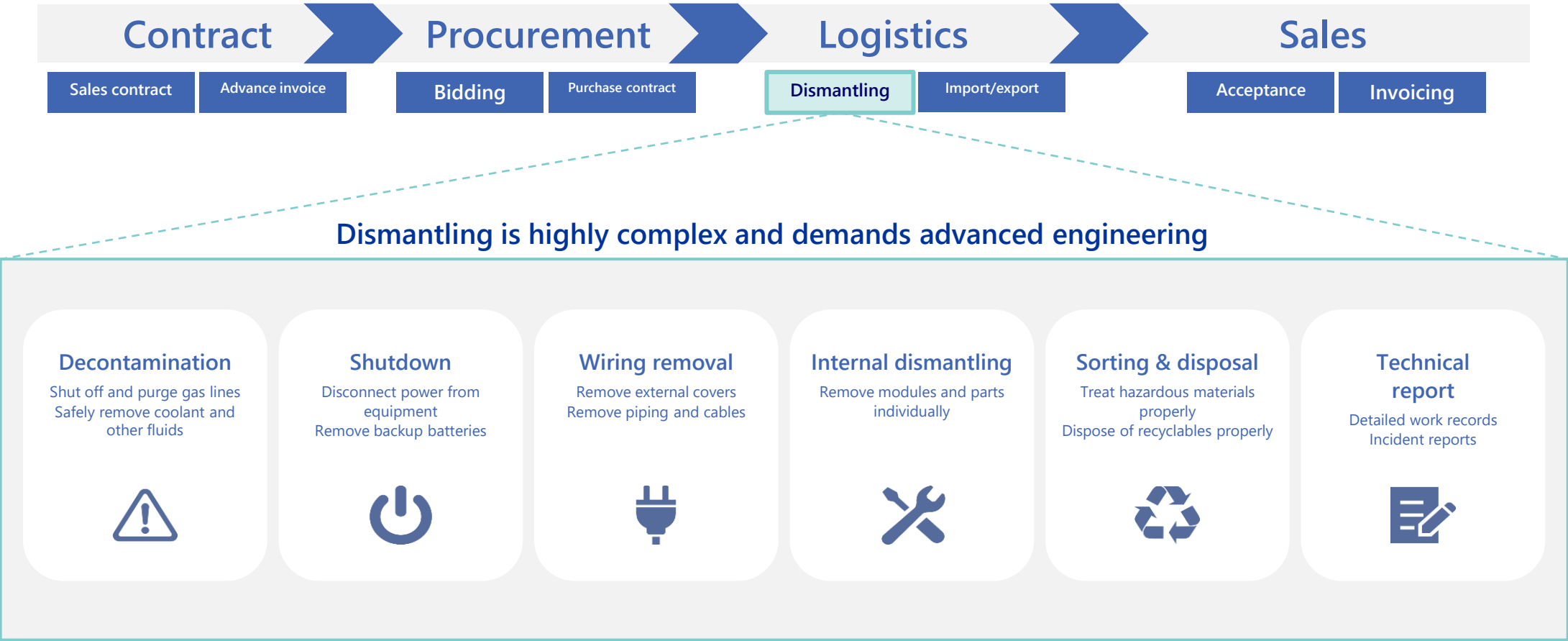
- Visualizing actual inventory, which was difficult with conventional procurement, **providing a platform that streamlines semiconductor equipment procurement**



Business Flow: Equipment Trading Process

Our in-house dismantling know-how, a prerequisite for equipment trading, accelerates transactions

- In-house handling of dismantling, the most important process in equipment trading
- Fast, reliable transactions backed by advanced engineering**



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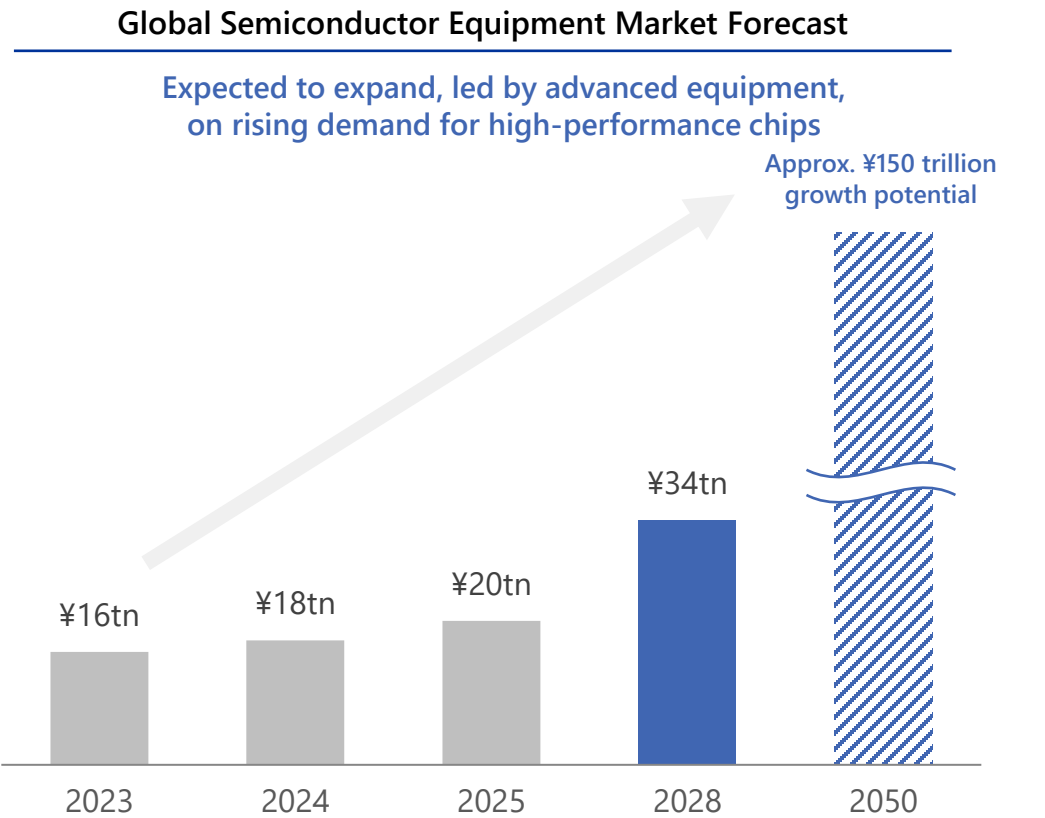
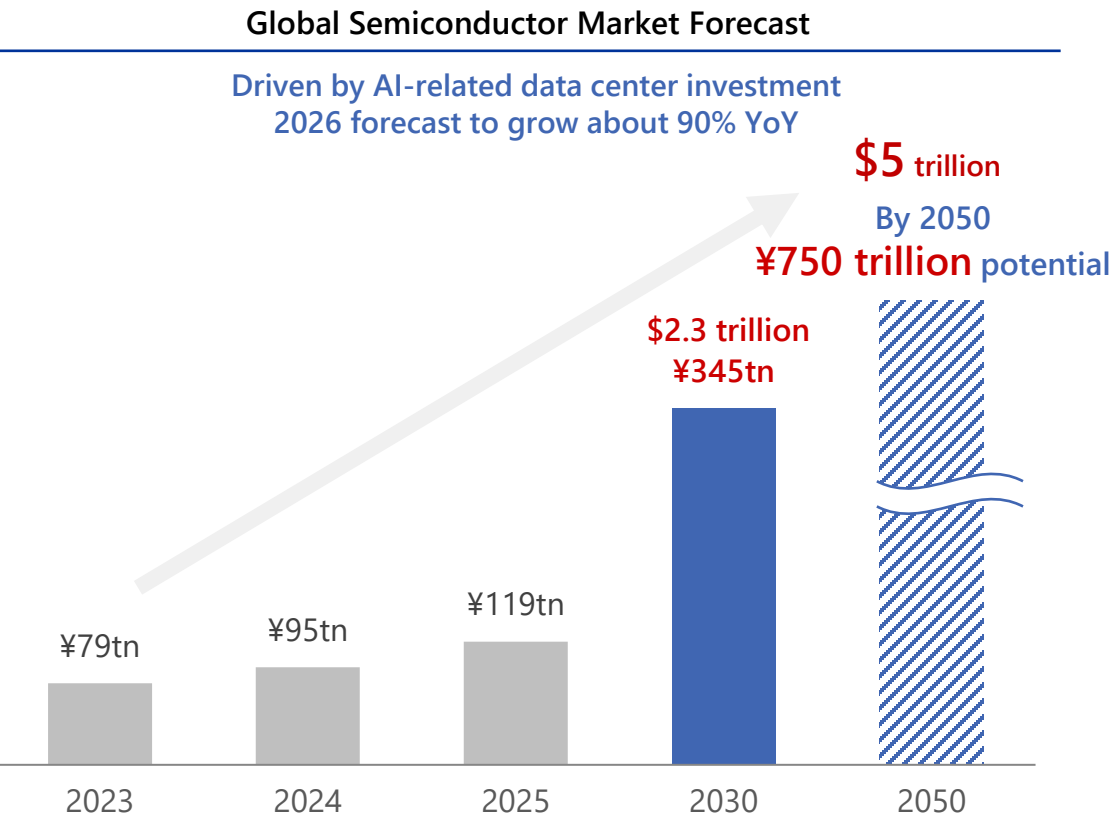
Business Overview / **Market Environment** /
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Appendix

Global Semiconductor Market Size

Growing to ¥345 trillion by 2030; rising market potential supports our growth strategy

- The global semiconductor market, driven by AI-related investment, is expected to exceed \$1 trillion for the first time in 2026, and to expand rapidly to ¥345 trillion (\$2.3 trillion) by 2030
Over the long term, it could grow to ¥750 trillion (\$5 trillion) by 2050
- The semiconductor manufacturing equipment market, our medium- to long-term target market, is also expanding steadily

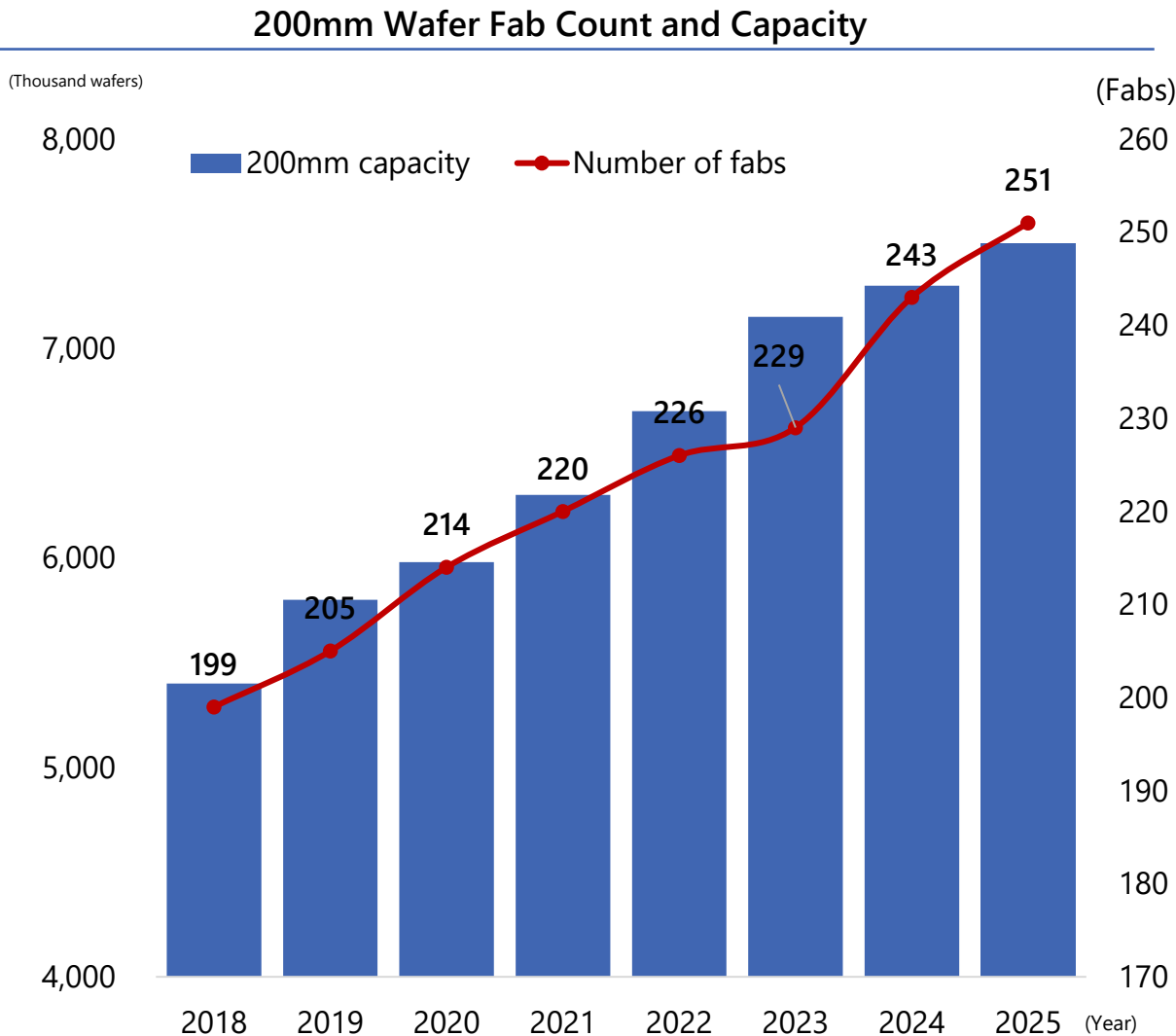


Sources: WSTS Japan, "WSTS Spring 2026 Semiconductor Market Forecast" (June 2026)
McKinsey & Company, "The \$2.3 trillion horizon" (Sept. 2026) *Converted at ¥150/USD
Tokyo Electron Ltd. website, "The Future of the Semiconductor Industry and its People"

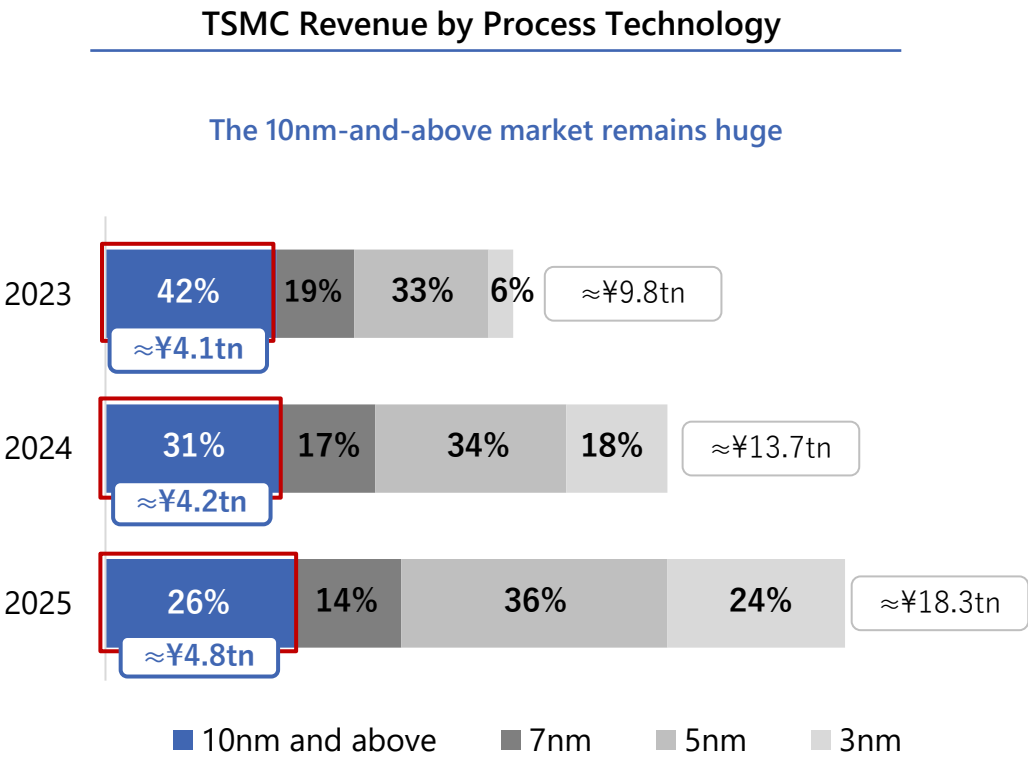
Sources: Estimated from SEMI "Year-End 2025 Equipment Forecast" (2023–2024),
SEMI equipment market statistics (2025 actual) and "Mid-Year Forecast" (July 2026; 2028 forecast)
2050 calculated assuming growth in line with the overall semiconductor market from 2025 actual
*Converted at ¥150/USD

Strong Demand for Legacy Semiconductors

200mm fab capacity growing rapidly amid chip shortages; legacy chips remain a mainstay even at leading-edge companies



Source: SEMI "200mm Fab Outlook" 2Q 2026 Update
*2024 and 2025 are actual-based figures from the latest public information (capacity rounded from published values)



FX: NT\$1 = ¥4.68 (2023), ¥4.73 (2024), ¥4.81 (2025)
Revenue: approx. NT\$2.10tn (2023), NT\$2.89tn (2024),
NT\$3.81tn (2025)

Source: Prepared by TMH from TSMC disclosures (FY2023, FY2024 and FY2025 actual)
2025 FX rate calculated from Mitsubishi UFJ Research and Consulting's 2025 average TTM
(US\$1 = ¥149.71) and TSMC's USD revenue (approx. US\$122.4bn)

The Importance of Older Semiconductor Equipment in the Global Market

Not only "leading-edge equipment" but also "older equipment" adapted to diverse uses is in high demand

- While investment in leading-edge fabs is active, demand for legacy semiconductors also remains high, and maintenance of older semiconductor equipment is as important a theme as leading-edge semiconductor development

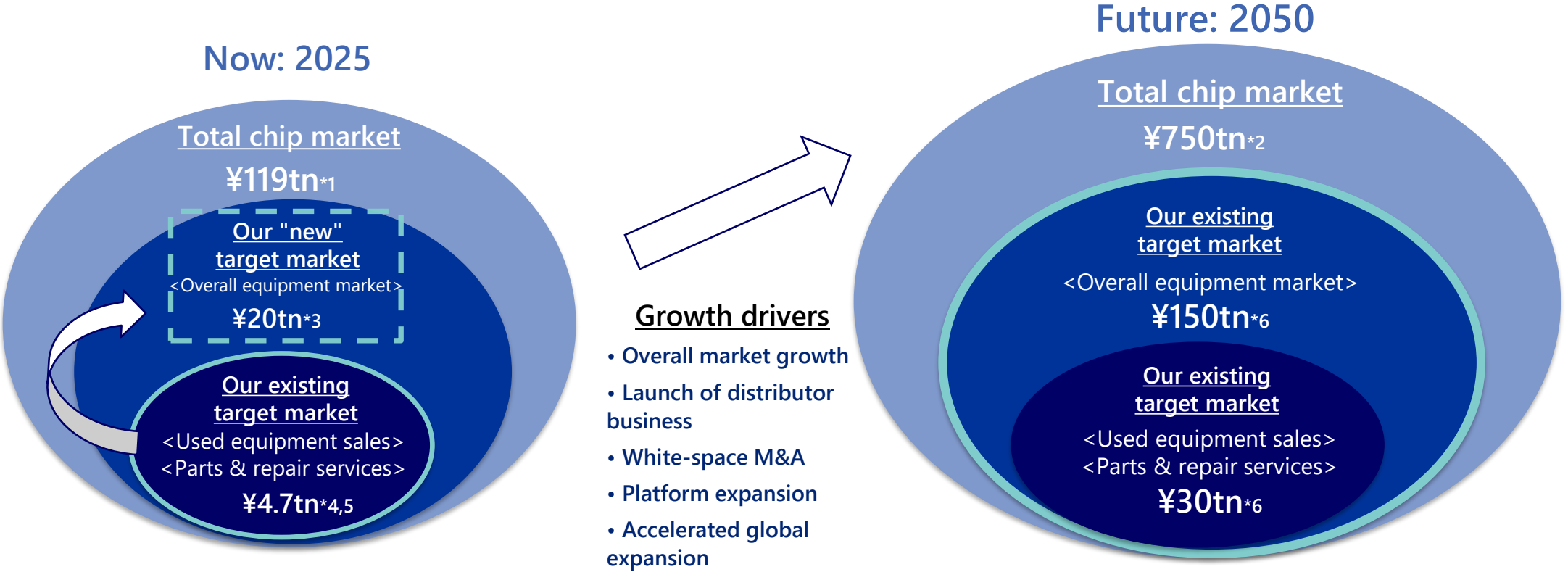
	Market current situation	investment trends
cutting edge	Against the backdrop of strong demand related to generative AI, data centers and Demand for high-performance cutting-edge semiconductors such as smartphones is extremely high.	In Japan, trillions of yen worth of investments are progressing through public-private cooperation, including TSMC-related investments and the development of miniaturization technology. Overseas, there are struggles for hegemony, including the United States and South Korea. Large-scale investment as a national policy becomes active
old model	Demand for power semiconductors, sensors, etc. that use older semiconductors continues to increase, mainly for IoT products and automobile-related products. Demand for semiconductors with low to medium performance is also strong. responsible for these Semiconductor manufacturing equipment invested over 20 years ago is still in operationThe current situation is that semiconductor factories operating in Japan are More than 80% are legacy factories with wafer sizes of 200mm or lessis	Old semiconductor manufacturing equipment is still very important. For example, India provides comprehensive support focusing on legacy factories. The ISM was launched as a national policy, etc. Equipment maintenance(procurement of EOL parts, repair, purchase of used equipment, start-up, improvement, etc.) Investments are being made globally

<About 200mm/300mm wafer size factory>
It refers to the diameter size of wafers, which are the material used to manufacture semiconductor chips. 200 mm wafers are a standard size that has been widely used in the past, but now larger 300 mm wafers, which have higher production efficiency, have become mainstream. Factories that use 200 mm wafers often use old technology and are sometimes called legacy factories.

Target Market

Expanding our target to the ¥20 trillion "overall equipment market" through the distributor business and M&A

- Our existing target markets, within the semiconductor market, are the used semiconductor equipment market and the parts & repair services market
- Through the launch of the semiconductor equipment distributor business and expected M&A strategies, we view the entire semiconductor equipment market as our medium- to long-term target



*1 Source: WSTS Japan, "WSTS Spring 2026 Semiconductor Market Forecast"

*3 Source: Estimated from SEMI equipment market statistics (2025 actual)

*6 2050 calculated assuming the same growth rate as the overall semiconductor market from 2025 actual

*2 Source: Tokyo Electron Ltd. website, "The Future of the Semiconductor Industry and its People"

*4 Source: The Business Research Company, "Used Semiconductor Equipment Global Market Report 2025"

*Converted at ¥150/USD

*5 Assumed to be 20% of the semiconductor equipment market

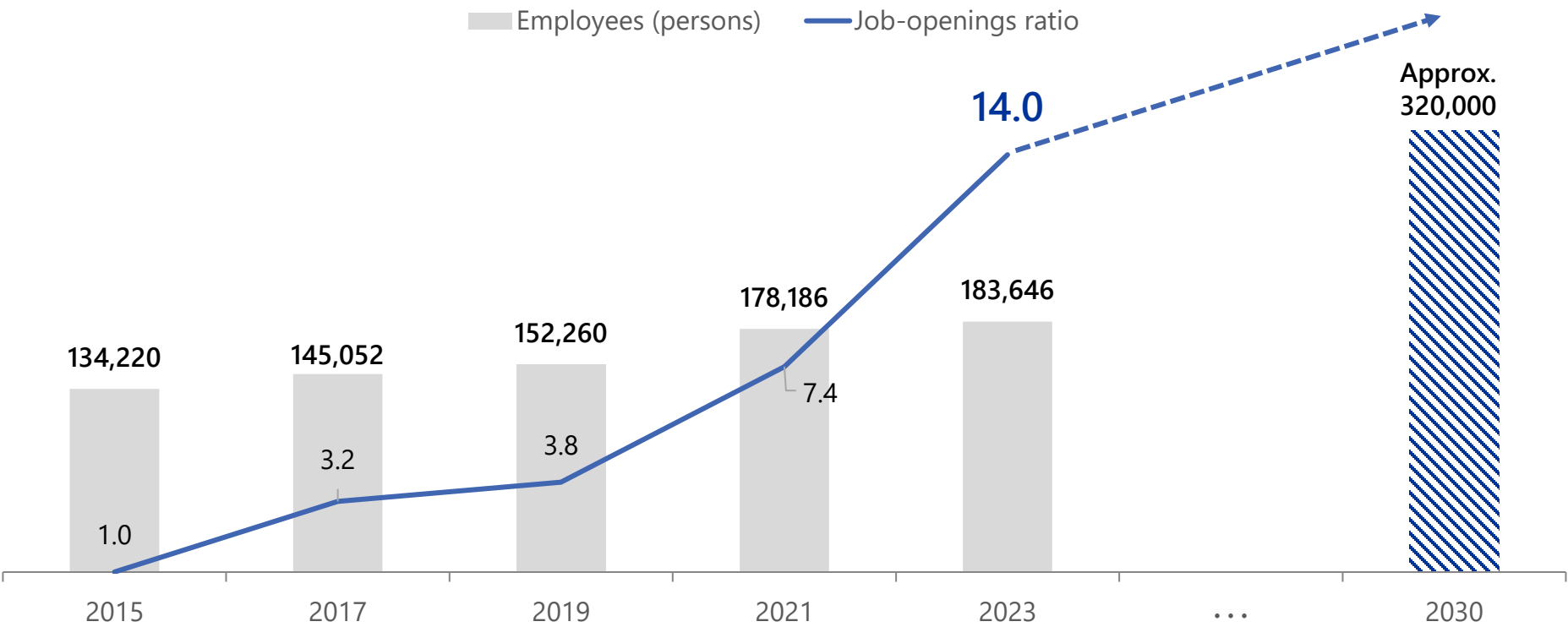
State of Domestic Semiconductor Fabs – Labor Shortage in the Semiconductor Industry

The semiconductor industry faces a serious labor shortage

- The semiconductor-related workforce is on an increasing trend, yet talent is already in short supply and the job-openings-to-applicants ratio is rising sharply
- Furthermore, new fab construction and the like are seen to require an additional ~140,000 people by 2030 (SEMI)

Talent supply could become a bottleneck for the semiconductor-related industry

Semiconductor-related-industry workforce trend and engineer job-openings ratio



Sources:

*1 Ministry of Economy, Trade and Industry, "Census of Manufactures," "Economic Structure Survey"

*2 Nikkei (SEMI executive: "By 2030, a global shortage of 1.5 million semiconductor workers"), Dec 12, 2024 article

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Our Sources of Value

Creating value through manufacturing support with ① platform capabilities and ② engineering capabilities



Conventional Supply Chain Challenges

- Parts shortages for aging equipment
- Supply chain disruption by disasters
- Disposal of unused equipment
- Shortage of engineers and other talent
- Declining competitiveness
- Aging semiconductor equipment
- Manufacturing innovation

Platform Capability

- Equipment & parts supply information
- Fab demand information
- Ability to build new platforms around semiconductor manufacturing

Engineering Capability

- Equipment dismantling, removal, installation
- Productivity improvement proposals
- Process tuning

Value TMH Provides

- Cross-border EC: procurement routes
- Parts repair & procurement
- Semiconductor talent platform
- Equipment dismantling/export
- Equipment start-up/improvement
- Improving end-product functionality

Solving customers' diverse challenges with ① Platform × ② Engineering capabilities

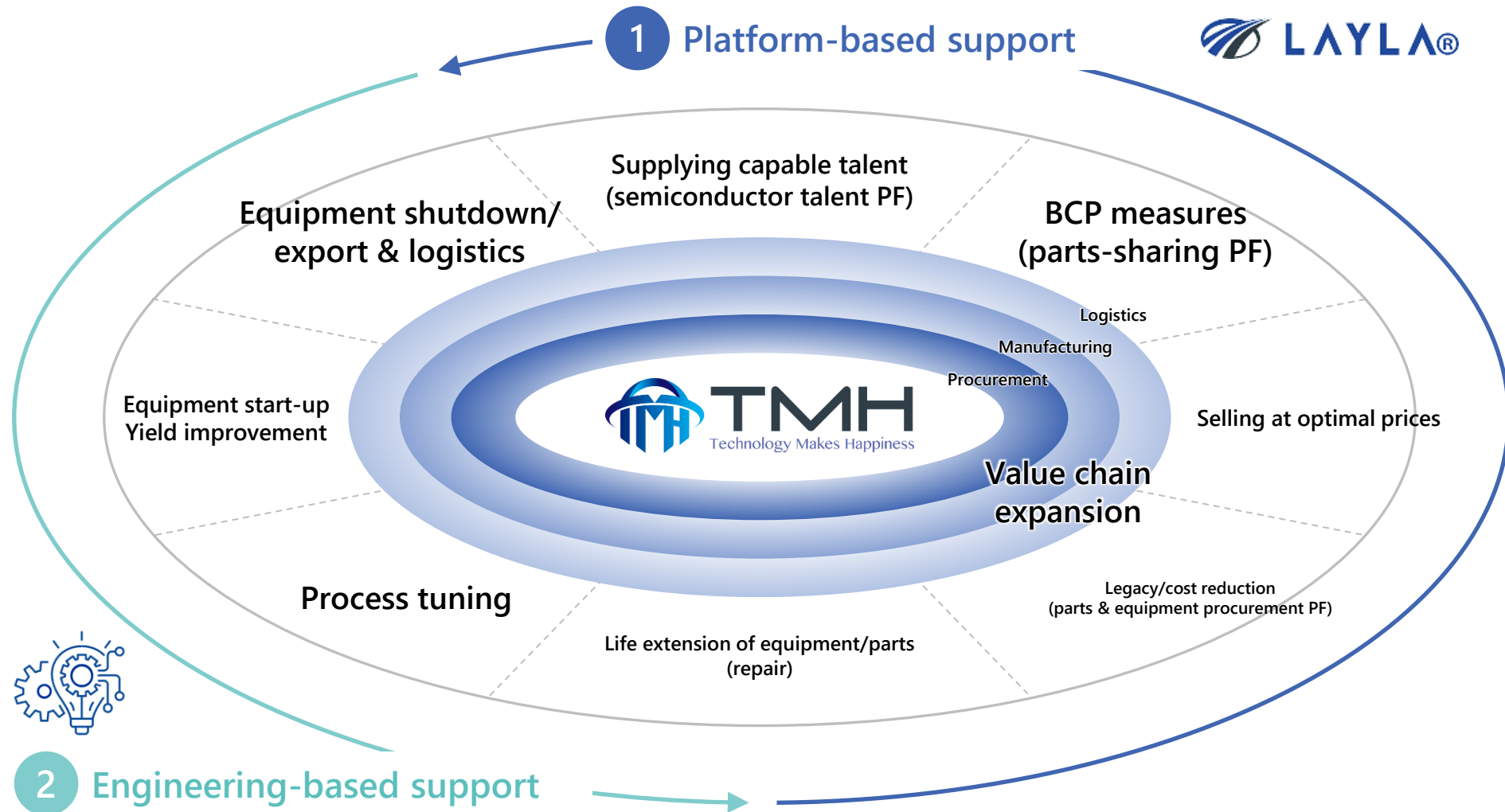
Improving corporate earnings and creating value



Accumulating Technology and Knowledge

Becoming irreplaceable to customers by addressing the diverse challenges of semiconductor fabs

- **Solving fab challenges** exposes us to diverse projects, improving our know-how and problem-solving capability
- Stable growth as an **information-intensive company** in semiconductor manufacturing



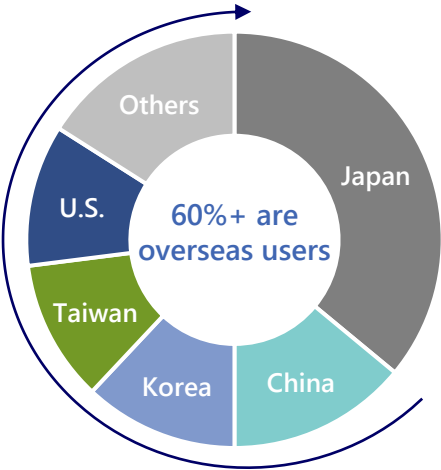
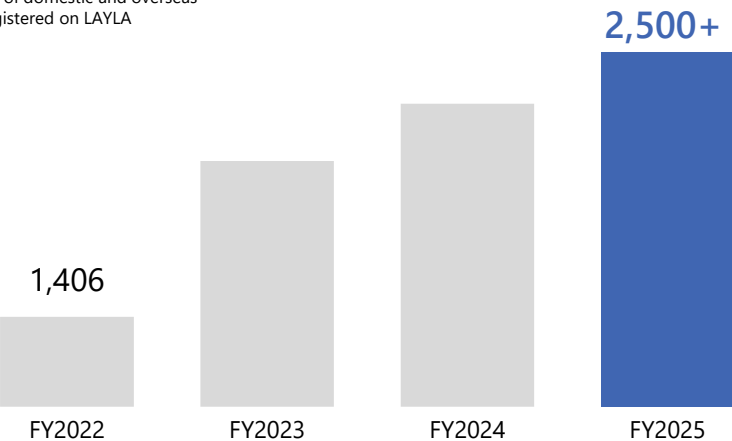
Platform Capability

LAYLA is becoming an indispensable platform for the semiconductor industry

- LAYLA-EC keeps expanding globally as a platform solving fabs' parts-procurement challenges
- In Japan, **over 50% of fabs have adopted LAYLA-EC**. It plays a key role in domestic chipmaking

Globally expanding user base

Users = total number of domestic and overseas buyers and sellers registered on LAYLA



Platform Value LAYLA-EC Provides to Users

Global procurement channels	Visualizing buried inventory	× Engineering capability
Multilingual support, cross-border payment, trade procedures, etc.: LAYLA-EC simplifies complex cross-border transactions	LAYLA-EC visualizes "buried" parts scattered across fabs worldwide	Beyond distributing parts, maintaining quality through sourcing alternatives (expert judgment) and audits
Cross-border procurement, difficult with conventional methods, is now possible	Established as the most effective procurement method for legacy fabs	Services that go beyond a simple parts procurement EC

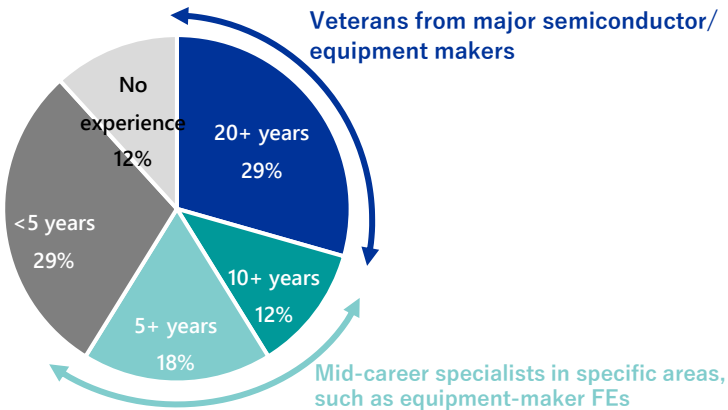
Engineering Capability

A globally recognized team of experts

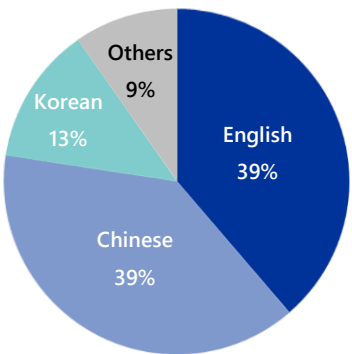
- A deep bench of semiconductor professionals with language skills and local business know-how in major chip countries
- End-to-end engineering for technical issues, from procurement to start-up, life extension and improvement

Globally recognized, including a supplier award from a major U.S. semiconductor maker

Experienced veterans and mid-career staff rare in the market



Language skills for major semiconductor countries



Source: As of end of November 2025 (excluding administrative staff)

Field Engineering

Beyond selling used semiconductor equipment, veteran and mid-career engineers who know "legacy equipment" inside out provide end-to-end support, from dismantling, removal (installation) and process tuning (equipment optimization) to productivity improvement and life extension.

Compounding Know-how

The globally expanding LAYLA platform aggregates knowledge, business practices and information from around the world. Synergy with experienced engineers creates engineering capabilities that competitors find hard to replicate.

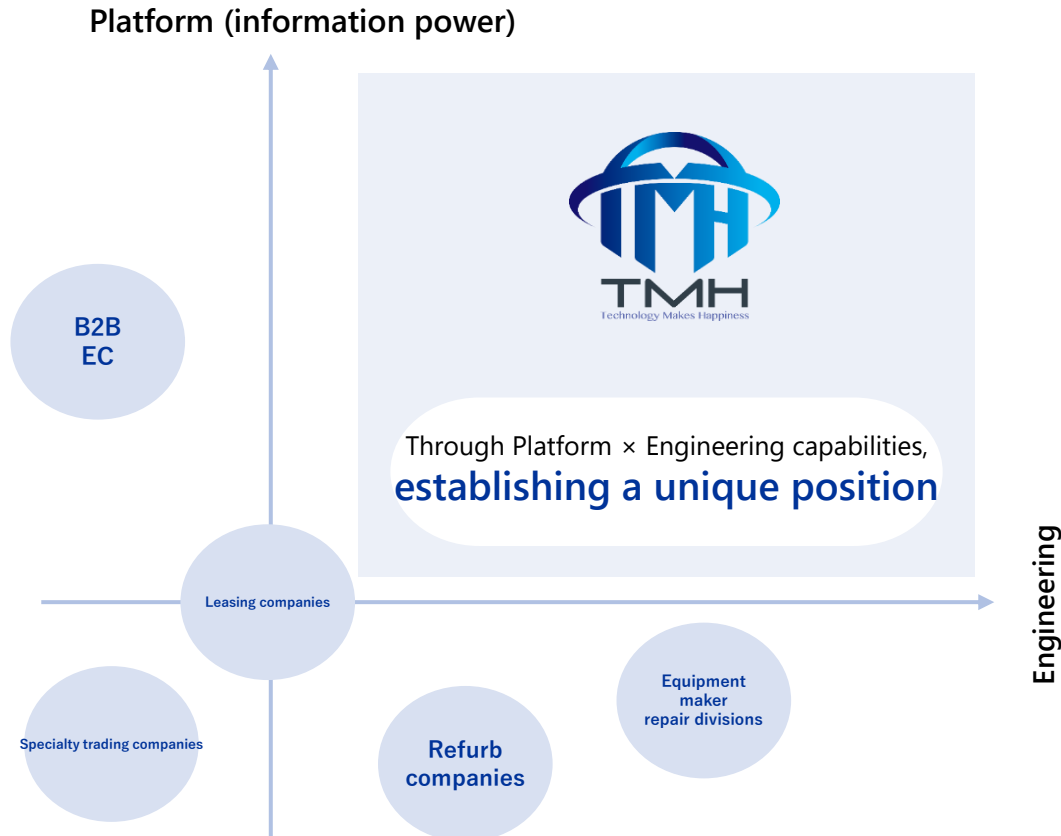
Expert Judgment

We source even hard-to-procure parts, including alternatives and from overseas. Our expert judgment of quality minimizes major risks of used parts, such as "bought it, but it doesn't work as expected."

Positioning Map

Establishing a unique position and creating a market as a niche-top player

Positioning vs. Competitors



Our Advantages & Barriers to Entry

01 High added value from engineering vs. leasing and trading companies

- Information power via our platform and expertise based on advanced engineering capabilities
- Providing advanced support such as equipment start-up and process tuning

02 Legacy fabs, multi-vendor support vs. semiconductor equipment makers

- Equipment makers focus on leading-edge fabs, while we broadly support semiconductor fabs including legacy fabs
- Equipment makers mainly handle their own products, while we handle products from all equipment makers and offer a broad service lineup

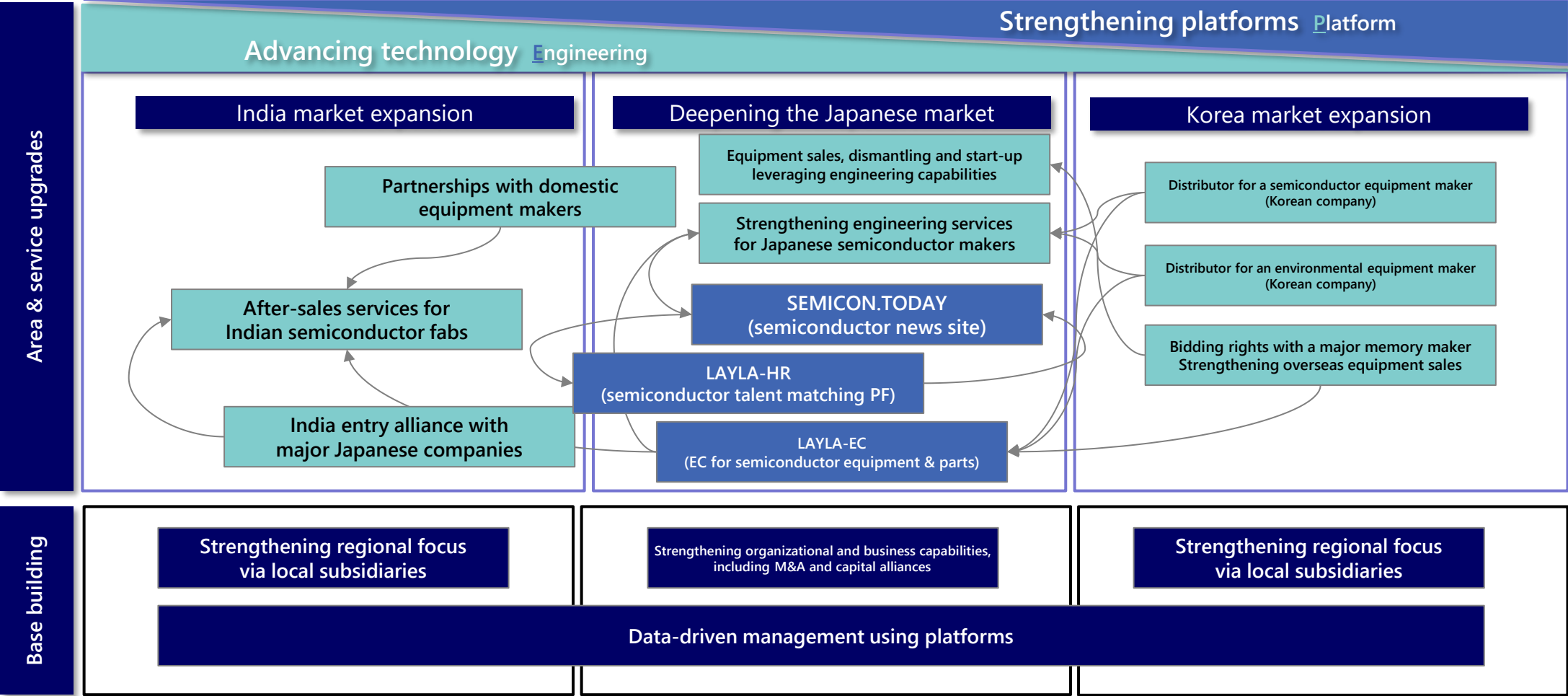
03 Strong customer base vs. new entrants

- Semiconductor manufacturing requires technical expertise, and with an established nationwide customer base and large share, we can maintain high barriers to entry

Initiatives to Achieve Medium-Term Margin Targets
Aiming for net sales (GMV) over ¥18bn and operating profit of ¥1.76bn through market and service expansion

Net sales (GMV) **¥18.0bn+** Operating profit **¥1.76bn**

Aim 2028



Appendix

FY2026 Forecast

Assumptions

(Unit: ¥ million)	Consolidated forecast	Assumptions
Net sales	3,179	
Equipment sales	1,958	Equipment sales services are estimated based on the current order backlog and sales plan
Parts sales & repair services	1,221	- Parts sales & repair services are estimated based on prior-year results and sales activity progress - Sales tend to increase as semiconductor fab utilization rises
Cost of sales	2,735	- Cost of sales varies with equipment sales margins and parts sales & repair services sales - Includes the valuation loss on equipment inventory expected in Q4
SG&A expenses	719	Expenses are estimated based on prior-year results, headcount increases and expansion plans
Non-operating income/expenses	Non-operating income 14 Non-operating expenses 23	- Estimated based on prior-year results, etc. - For FX, large transactions such as equipment sales are generally yen-denominated to minimize FX risk - Parts sales & repair services include foreign-currency transactions, but because sales recognition and collection, and purchase recognition and payment, occur close together, the impact is assumed to be minor

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